

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Janak G. Patel

Examiner: Unassigned

Serial No.: Unassigned

Group Art Unit: Unassigned

Filed: Herewith

Docket: END920030066US1 (16897)

For: **METHOD AND STRUCTURE
TO SUPPORT HEAT SINK
ARRNGEMENT ON CHIP
CARRIER PACKAGES**

Dated: October 7, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R. §§ 1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

1. U.S. Patent No. 6,430,050 B1, dated August 6, 2002 to Hensley, et al.;
2. U.S. Patent No. 6,392,887, dated May 21, 2002 to Day, et al.;
3. U.S. Patent No. 6,362,516 B1, dated March 26, 2002 to Waters;

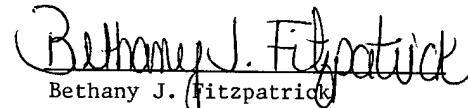
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I hereby certify that this correspondence is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. §1.10 on the date indicated above and is addressed to the Commissioner of Patents, Alexandria, VA 22313-1450 on 10/07/03.

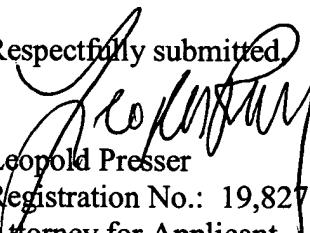
Dated: 10/7/03


Bethany J. Fitzpatrick

4. U.S. Patent No. 5,870,285, dated February 9, 1999 to Kosteva, et al.;
5. U.S. Patent No. 5,863,814, dated January 26, 1999 to Alcoe, et al.; and
6. IBM Technical Disclosure Bulletin "Air-Cooled Module Heat Dissipation", G. Dumaine, et al.; Vol. 20, No. 4, September 1977.

Applicants are submitting copies of the above-cited IBM Technical Disclosure Bulletin.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R. § 1.97(b), no statement or fee is required.

Respectfully submitted,

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Atty. Docket N .
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LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

Applicant
Janak G. Patel

**Filing Date
Herewith**

U.S. PATENT DOCUMENTS

EXAMINER INITIAL*		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	AA	6,430,050 B1	8/6/02	Hensley, et al.			
	AB	6,392,887	5/21/02	Day, et al.			
	AC	6,362,516 B1	3/26/02	Waters			
	AD	5,870,285	2/9/99	Kosteva, et al.			
	AE	5,863,814	1/26/99	Alcoe, et al.			
	AF						
	AG						
	AH						

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

IBM Technical Disclosure Bulletin "Air-Cooled Module Heat Dissipation", G. Dumaine, et al.; Vol. 20, No. 4, September 1977

EXAMINER

DATE CONSIDERED

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.